

Nurul Razliana Abdul Razak

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Microstructure, thermal behavior and joint strength of Sn-0.7Cu-1.5Bi/electroless nickel immersion gold (ENIG). Journal of Materials Research and Technology, 2021, 12, 1700-1714.	5.8	8
2	Influence of Bismuth in Sn-Based Lead-Free Solder – A Short Review. Solid State Phenomena, 0, 273, 40-45.	0.3	4
3	Physical and Mechanical Behaviors of SnCu-Based Lead-Free Solder Alloys with an Addition of Aluminium. Applied Mechanics and Materials, 2015, 815, 64-68.	0.2	3
4	Temperature dependency of the growth rate of (Cu,Ni) ₆ Sn ₅ on Cu-xNi substrates. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012007.	0.6	3
5	Effect of surface finish on the wettability and electrical resistivity of Sn-3.0Ag-0.5Cu solder. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012029.	0.6	3
6	In-situ observation of high-temperature Pb-free electric interconnections by synchrotron microradiography. Materials Letters, 2021, 291, 129520.	2.6	3
7	Effect of Aluminium Addition on Microstructure and Microhardness of Sn-0.7Cu-xAl Lead-Free Solder Alloy. Applied Mechanics and Materials, 2015, 754-755, 166-170.	0.2	2
8	Mechanical Properties and Solderability of Robust Sn-0.7Cu Lead-Free Composite Solder. Applied Mechanics and Materials, 0, 754-755, 556-560.	0.2	2
9	The Effects of Zinc Addition on the Microstructure, Melting Point and Microhardness of Sn-0.7Cu Lead-Free Solder Fabricated via Powder Metallurgy Method. Materials Science Forum, 2016, 857, 13-17.	0.3	2
10	Development of Low Cost Sn-0.7Cu Base Composite Solder for High Temperature Application. Materials Science Forum, 0, 803, 239-242.	0.3	1
11	Interfacial reactions between different Sn-based lead-free solder alloys and CuNi substrates. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012008.	0.6	1
12	Enhancement on wettability and intermetallic compound formation with an addition of Al on Sn-0.7Cu lead-free solder fabricated via powder metallurgy method. AIP Conference Proceedings, 2016, , ,	0.4	0
13	Enhancement of Microstructural and Physical Properties of Sn-0.7Cu Lead-Free Solder with the Addition of SiC Particles. Solid State Phenomena, 2018, 280, 181-186.	0.3	0
14	Physical properties of Sn-3.0Ag-0.5Cu lead-free solder with the additional of SiC particles. IOP Conference Series: Materials Science and Engineering, 2019, 701, 012030.	0.6	0